

ABSTRACT OF THE DISCLOSURE

A conductive ball mounting method for mounting conductive balls on a mount using an arraying mask, in which the mount includes mounting positions formed in a predetermined pattern, and the arraying mask is provided above the mount and includes through holes provided in positions corresponding to the mounting positions. The method includes providing a ball suction unit for sucking solder balls, the ball suction unit including a ball holding member capable of holding the conductive balls, sucking up the conductive balls below the ball suction unit, holding the conductive balls on a lower surface of the ball holding member while sucking up the conductive balls, and after the holding the conductive balls, falling the conductive balls held by the ball holding member to the mount.